

## PRODUCT ADVANTAGE

Excellent Pull Strength at 285°C  
High Temperature Applications  
(>300°C)  
Removes Additional Gluing Processes  
Excellent Process Compatibility  
High Reliability  
100% Reworkable

## OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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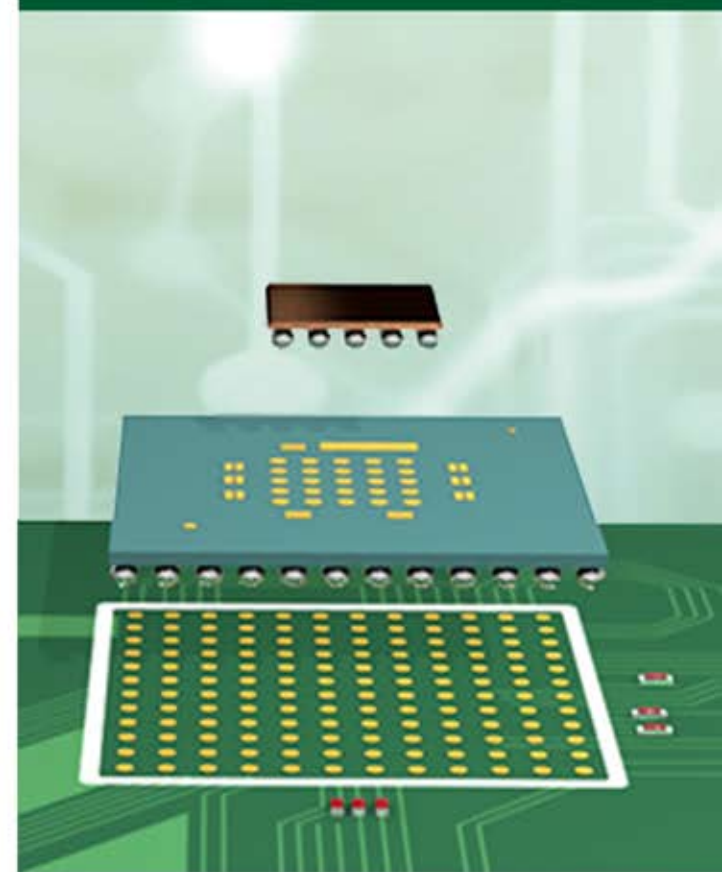
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YPB-004 (Version 5/2017)



INNOVATION AT ITS BEST

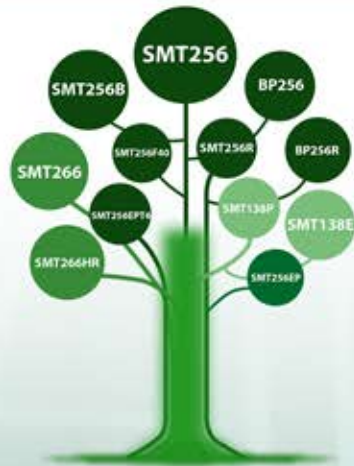


SMT 256EP  
SOLDER JOINT  
ENCAPSULANT PASTE  
OVERVIEW

*Preferred by global leaders in the  
electronics manufacturing industry*



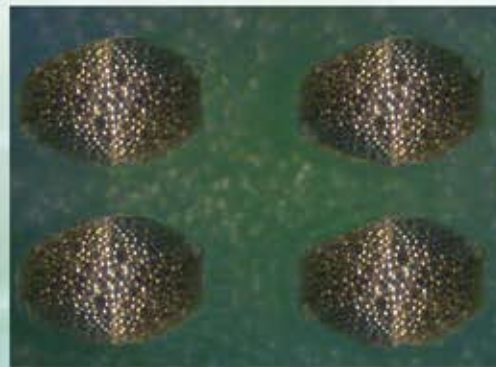
# YINCAE® SMT 256EP Encapsulant Paste



Solder Joint Encapsulants

SMT 256EP is capable of being used at high temperatures for double reflow applications and can prevent components from falling off during this process

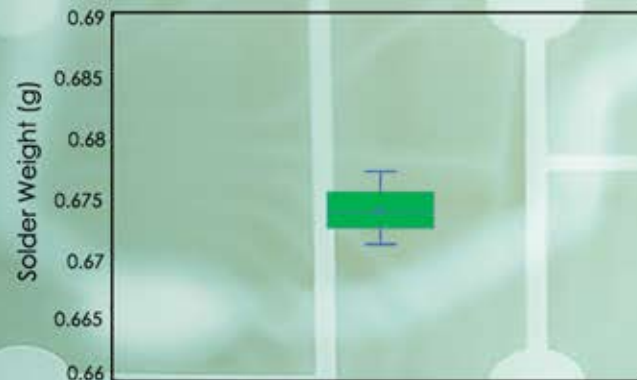
Availability  
 SMT 256EP T4: Printing  
 SMT 256EP T6: Dispense (#27)  
 SMT 256EP T6: Dispense (#30)



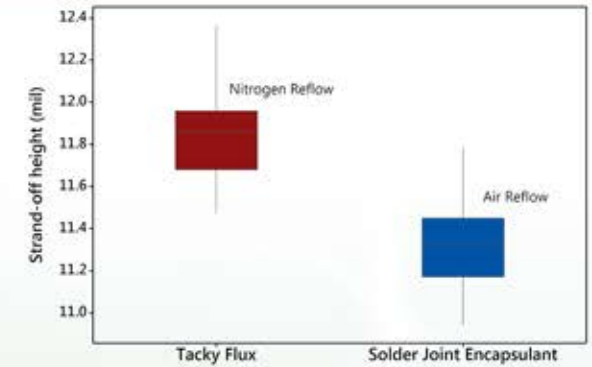
SMT 256EP printed on 50 µm stencil

The YINCAE® SMT 256EP Solder Joint Encapsulant paste is a combination of solder paste and a solder joint encapsulant, and is designed to enhance solder joint reliability and eliminate solder joint cracking in CSP, BGA, flip chips and POP microchip applications. This product removes metal oxide and allows individual solder joints to be formed, encapsulated by 3-D polymer network.

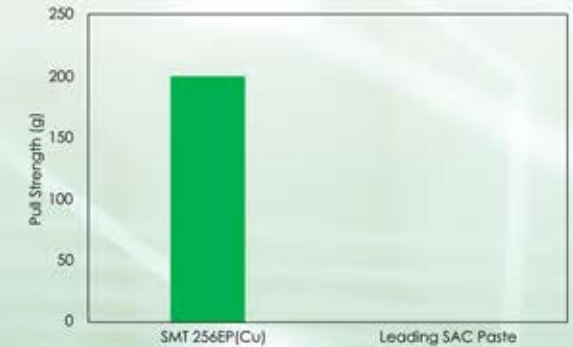
Compared to conductive solder adhesives, SMT 256EP offers a higher and more stable thermal and electrical conductivity.



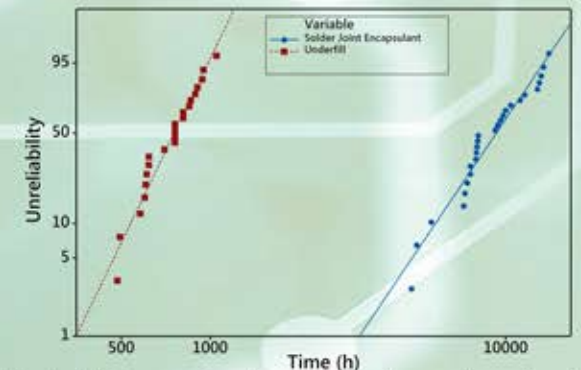
SMT 256EP weight consistency (data averaged from over 700 components)



SMT 256EP provides better soldering wetting in air reflow than tacky flux in nitrogen reflow



SMT 256EP shows a greater pull strength at high temperatures (285°C) than current leading SAC paste



Solder Joint Encapsulant enhances thermal cycling 10x, than tacky flux. (Thermal Cycling Conditions: SAC305; I/O 1156; -55°C~150°C; 1h/cycle.)